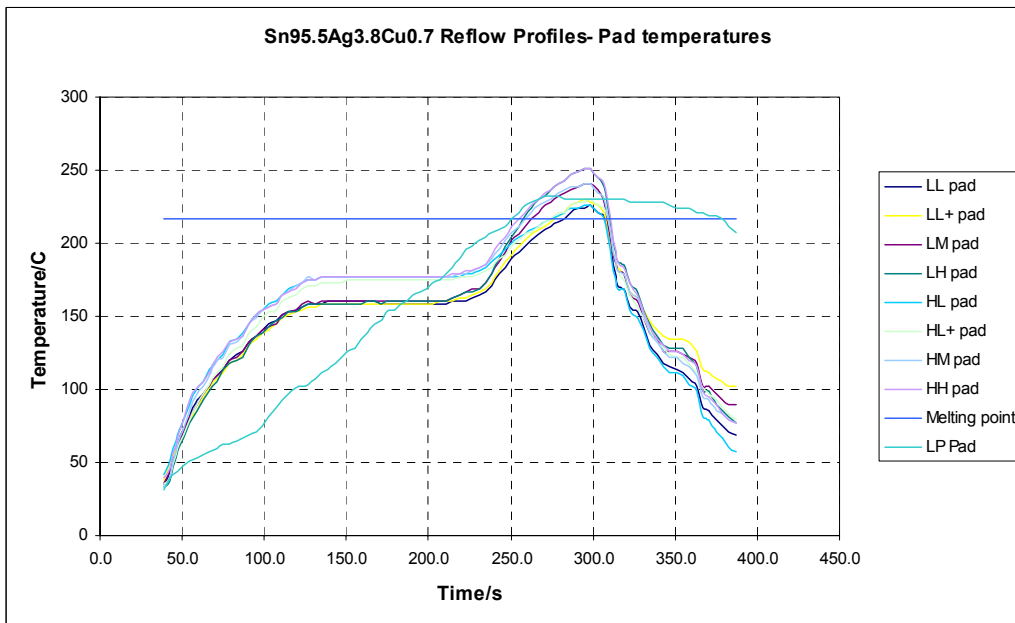




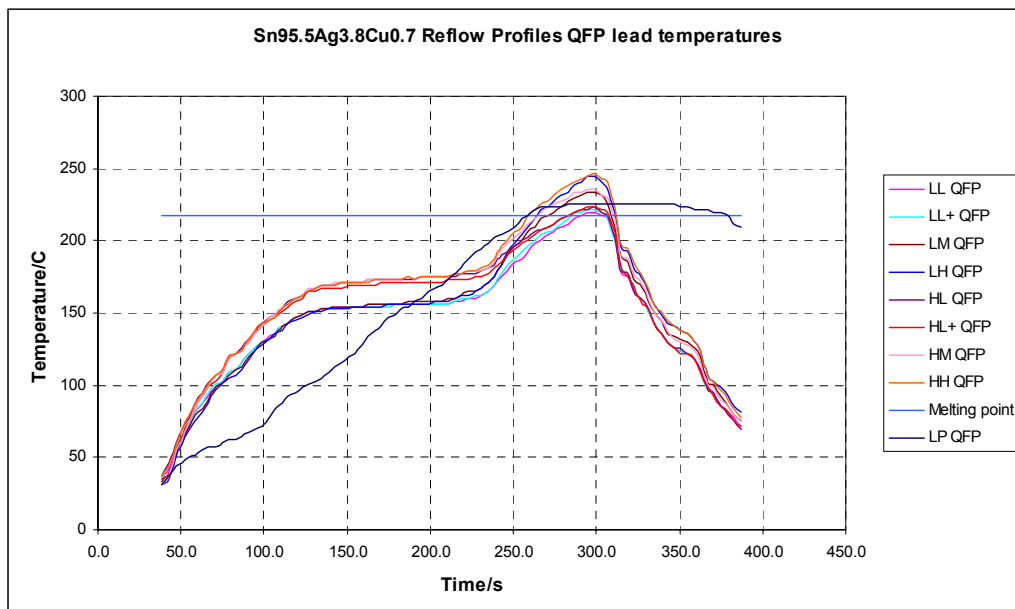
TYPICAL REFLOW PROFILE

Sn95.5Ag3.8Cu0.7 Lead Free Alloy



Typical reflow profile of solder pads across a double euro size SMT assembly using the Sn95.5Ag3.8Cu0.7 Lead Free Alloy

Reflow system was a Heller Hot Air Convection reflow oven



Typical reflow profile for Quad Flat Pack (QFP 32) leads using the Sn95.5Ag3.8Cu0.7 Lead Free Alloy

Reflow system was a Heller Hot Air Convection reflow oven